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(54) Title: THICK FILM-FORMING COMPOSITION AND METHOD FOR MANUFACTURING CURED FILM USING THE
SAME

(57) Abstract: A thick film-forming composition comprising a hydrocarbon- containing compound (A) having a certain structure and
a solvent (B): wherein, the solvent (B) comprises an organic solvent (B1) and an organic solvent (B2) having a dielectric constant of
20.0 to 90.0; and the film thickness of the film formed from the thick film-forming composition is 0.5 to 10 μ m.

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